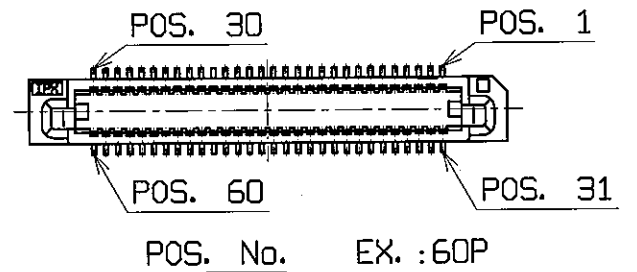
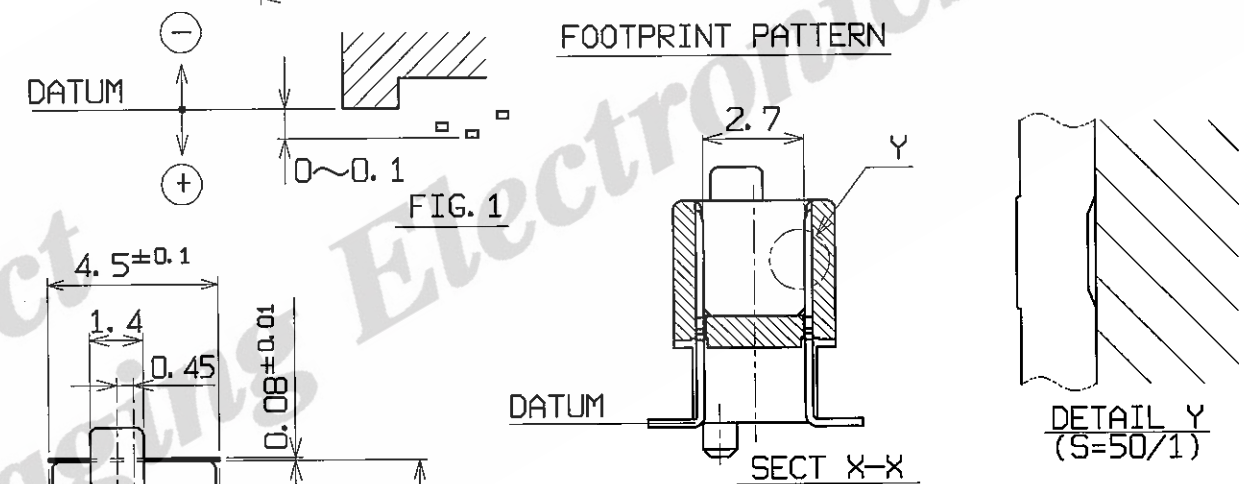
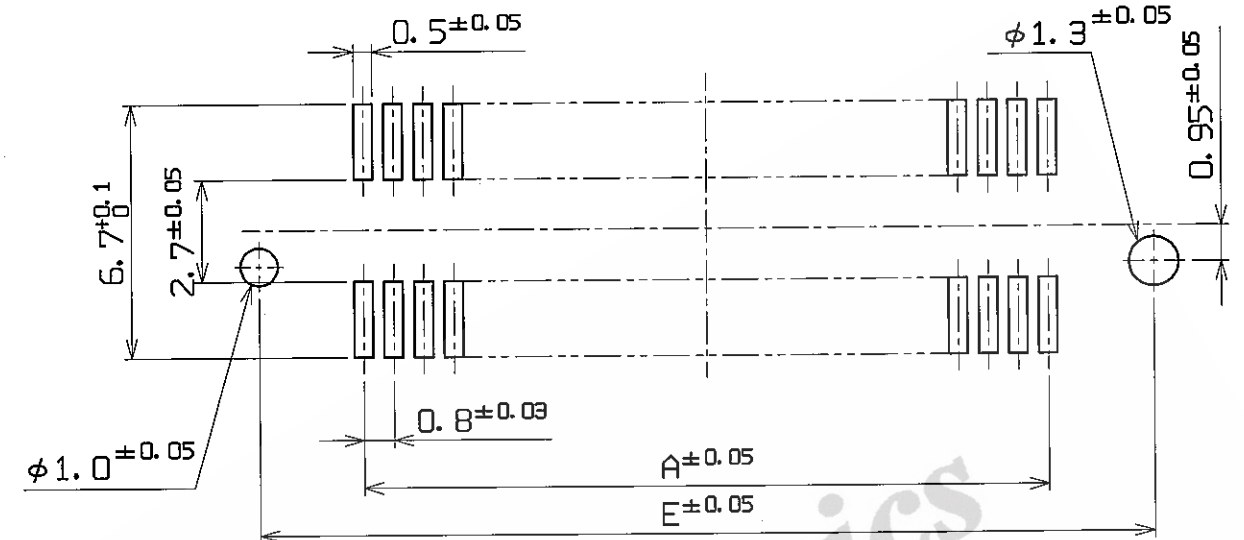
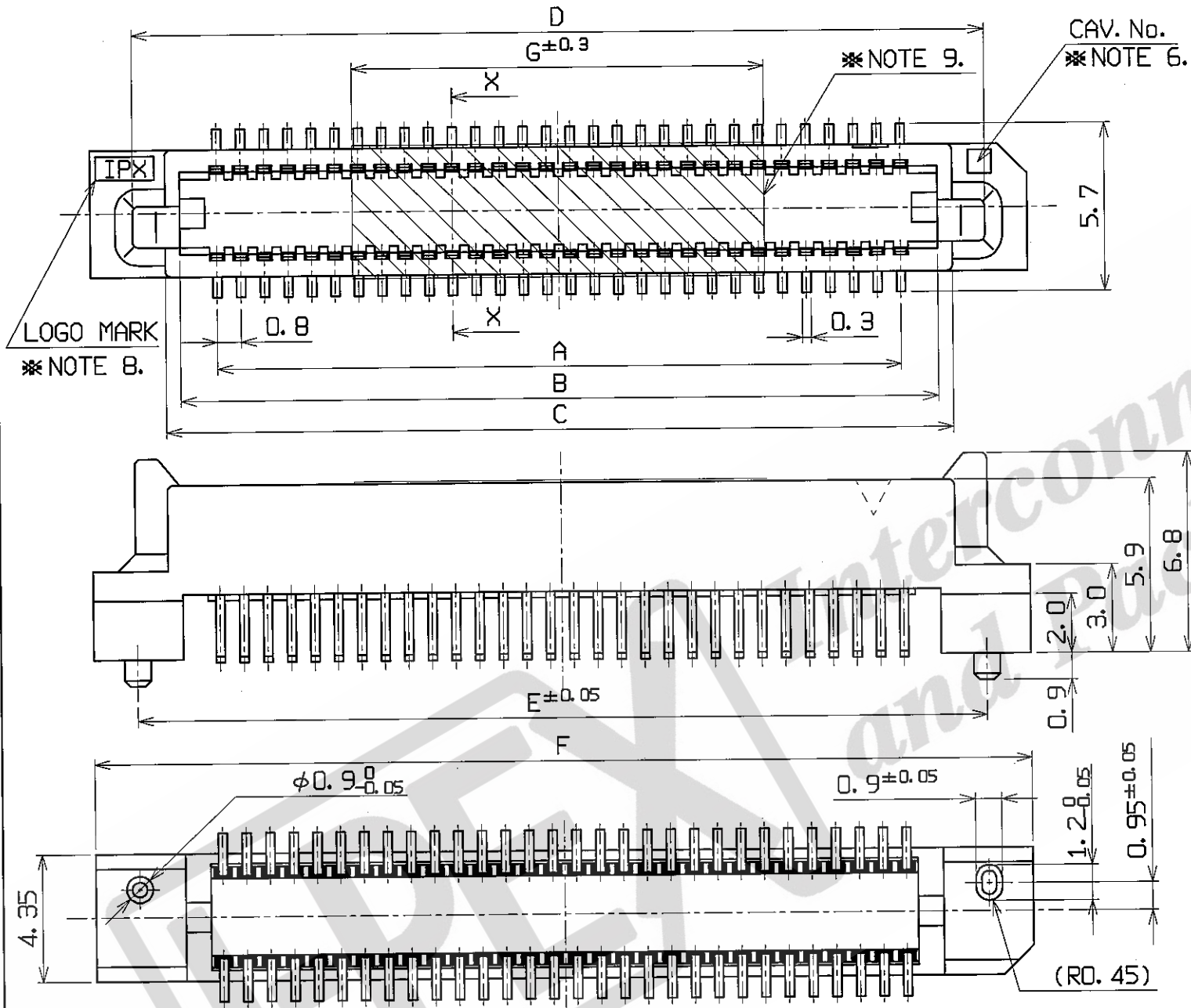


20003-100-#F	100	39.2	41.7	42.7	44.9	44.8	47.8	
20003-080-#F	80	31.2	33.7	34.7	36.9	36.8	39.8	
20003-060-#F	60	23.2	25.7	26.7	28.9	28.8	31.8	14.0
20003-050-#F	50	19.2	21.7	22.7	24.9	24.8	27.8	
20003-040-#F	40	15.2	17.7	18.7	20.9	20.8	23.8	
20003-030-#F	30	11.2	13.7	14.7	16.9	16.8	19.8	B.0
20003-020-#F	20	7.2	9.7	10.7	12.9	12.8	15.8	
20003-012-#F	12	4.0	6.5	7.5	9.7	9.6	12.6	6.0
PART No.	PIN	A	B	C	D	E	F	G

PART NO.	PIMPLE
20003-...-00F	NO
20003-...-01F	YES

☆EXAMPLE  
 20003-060-#F : TUBE PACKAGE  
 20003-060E-0#F : EMBOSS TAPING PACKAGE  
 (ONLY 12~80 POS.)



		DIM * H'		
PLUG	RECE	S(20004)	M(20005)	L(20006)
S(20001)		5.0	6.0	7.0
M(20002)		6.0	7.0	8.0
L(20003)		7.0	8.0	9.0

STACKING HEIGHT

NOTES  
 1. MATERIAL/FINISH  
 INSULATOR : GLASS REINFORCED LCP UL94V-0 (NATURAL)  
 CONTACT : COPPER ALLOY UNDER PLATED NI 1.27μm MIN.  
 CONTACT AREA : Au PLATED 0.5μm MIN.  
 OTHERS : Au PLATED 0.03~0.07μm  
 ADHESION TAPE : PI t=0.08±0.01

2. CURRENT RATING 0.5A  
 3. WITHSTANDING VOLTAGE AC300V 1MINUTE  
 4. INSULATION RESISTANCE DC250V 1,000ΩMIN.  
 5. CONTACT RESISTANCE 40mΩMAX.  
 \*6. CAV. No. (A, B...)  
 7. 20003-...-0#F : SEE 300-454 OF THE PACKING STANDARD.  
 20003-...-E-0#F : SEE 300-456 OF THE PACKING STANDARD.  
 \*8. LOGO MARK INCLUDE THE INSC. BASE.  
 \*9. ADHESION TAPE FOR EMBOSS TAPING PACKAGE.

DESIGN'D BY	M. TSUTSUMI	DATE	07/07/94
CHK'D BY	Y. H	DATE	07/08/94
APP'D BY	Y. FUKUDA	DATE	07/11/94
REV. RECORD	18 206404 K.T Aug./21/06 7.4	CUSTOMER COPY	PROJECTION
SERIES No.	2011	SCALE	5/1
		UNIT	mm
		DWG. No.	20003
		SHEET	1/1
		REV.	18